



Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model

[List multiple models if applicable.]

HP Chromebook x360 11 G1 Education Edition

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

| Item Description | Notes | Quantity of items included in product |
|--|---|---------------------------------------|
| Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) | With a surface greater than 10 sq cm 5-13M/B | 1 |
| Batteries | All types including standard alkaline and lithium coin or button style batteries Battery pack | 1 |
| Mercury-containing components | For example, mercury in lamps, display backlights, scanner lamps, switches, batteries | 0 |
| Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm | Includes background illuminated displays with gas discharge lamps | 1 |
| Cathode Ray Tubes (CRT) | | |
| Capacitors / condensers (Containing PCB/PCT) | | |
| Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height | | |
| External electrical cables and cords | power cord | 1 |
| Gas Discharge Lamps | | |
| Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above) | | |
| Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | |
| Components and waste containing asbestos | | |

| | | |
|--|--|--|
| Components, parts and materials containing refractory ceramic fibers | | |
| Components, parts and materials containing radioactive substances | | |

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

| Tool Description | Tool Size (if applicable) |
|------------------|---------------------------|
| Screw driver | #0 |
| Description #2 | |
| Description #3 | |
| Description #4 | |
| Description #5 | |

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove screw from D base x 7pcs
2. Release screw from D base center x 2pcs
3. Remove C top sub-Assy. from unit
4. Dis-connect Battery cable ,K/B membrane, TP FFC, Camera FFC connector from M/B
5. Remove TP FFC from TP module
6. Remove screw M2L2.5 x 3 on TP support bracket
7. Remove TP support bracket from C top sub-Assy.
8. Remove screw M2L2 x 3 on TP holder bracket
9. Remove TP holder bracket & TP module & TP mylar from C top sub-Assy.
10. Remove power FFC from D/B Pow.
11. Remove screw M2L3.5 x 2 on D/B Pow.
12. Remove D/B Pow. from D base sub-Assy.
13. Dis-connect speaker connector from M/B
14. Remove screw M2L3.5 x 3 on speaker box L / R
15. Remove speaker from unit
16. Dis-connect battery pack connector from M/B
17. Remove screw M2L3.5 x2 on battery pack
18. Remove screw M2L3.5 x1 on battery pack
19. Remove battery pack from unit
20. Dis-connect D/B & POWER/B FFC connectors from D/B & M/B
21. Remove D/B & POWER/B FFC
22. Remove screw M2L3.5 x 1 on D/B
23. Remove D/B from unit
24. Dis-connect LCD cable connector from M/B
25. Remove WLAN antenna cable from WLAN module
26. Remove screw M2L2 x 1 on WLAN module
27. Remove WLAN module from unit
28. Remove screw M2L3 x 5 on M/B
29. Remove M/B from unit
30. Remove screw M2L2 x 2 on thermal plate
31. Remove thermal plate from M/B
32. Remove antenna cable & LCD cable from unit
33. Remove screw L2.5L4.5 x 4 on hinge L / R bracket
34. Remove LCD sub-Assy. from unit
35. Remove glass with bezel from LCD sub-Assy.

36. Remove right side hinge screw for LCD cover
37. Dis-connect LCD cable connector from LCM
38. Remove screw M2.5L3.5 x 6 on hinge L / R bracket ears
39. Remove screw M2L2.5 x 2 on hinge L / R bracket
40. Remove hinge L / R from LCD sub-Assy.
41. Dis-connect LCD cable connector from Cam. module
42. Remove LCD cable from LCD sub-Assy.
43. Remove Cam. module from LCD sub-Assy.
44. Remove antenna cable from LCD sub-Assy.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total



3.22 Remove base screw

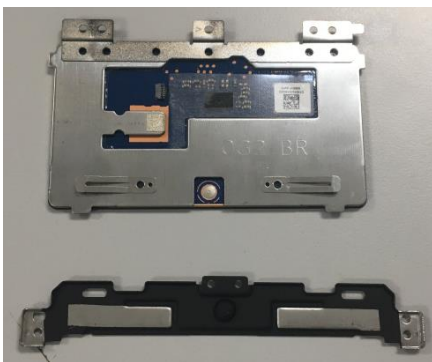


3.23 Remove TOP assy..





3.24 Remove TP support bracket & TP module

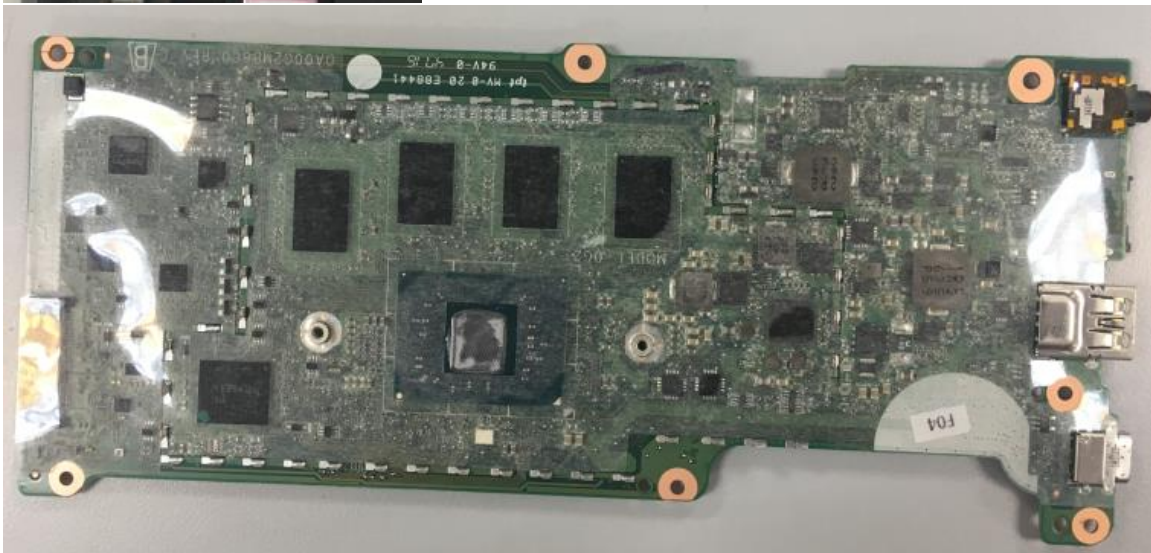


3.25 Remove speaker & battery pack & WLAN module



3.26 Remove D/B & D/B FFC & POWER Board & M/B







3.27 Remove LCD bezel with Glass



3.28 Remove right side hinge



3.29 Remove camera module and hinge -L & LCD cable & antenna cable

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PSG instructions for this template are available at [EL-MF877-01](#)



